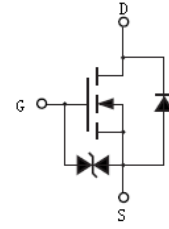


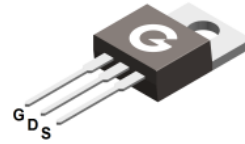
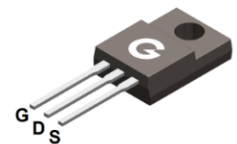
Features

- Fast switching
- ESD Improved Capability
- Low gate charge
- Low Reverse transfer capacitances
- HBM: JESD22-A114-B: 2

HF


Mechanical Data

- Case: TO-220AB, ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matted-Tin plated; solderability-per MIL-STD-202, Method 208


TO-220AB

ITO-220AB

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL10N70K	TO-220AB	50 pcs / Tube	10N70K
BL10N70KF	ITO-220AB	50 pcs / Tube	10N70KF

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	700	V
Gate-to-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (T _C = 25°C)	I _D	10	A
Continuous Drain Current (T _C = 100°C)		6.3	A
Pulsed Drain Current (t _p = 10μs, T _C = 25°C)	I _{DM}	40	A
Single Pulse Avalanche Energy ²	E _{AS}	700	mJ
Power Dissipation (TO-220AB, T _C = 25°C)	P _D	130	W
Power Dissipation (ITO-220AB, T _C = 25°C)		50	W
Operating Junction Temperature Range	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case (TO-220AB)	R _{θJC}	-	-	0.96	°C/W
Thermal Resistance Junction-to-Case (ITO-220AB)		-	1.9	2.5	°C/W
Thermal Resistance Junction-to-Air (TO-220AB)	R _{θJA}	-	-	50	°C/W
Thermal Resistance Junction-to-Air (ITO-220AB)		-	-	62.5	°C/W

Electrical Characteristics

(@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	700	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 700V, V _{GS} = 0V	-	-	10	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	-	-	±10	μA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance ^{*1}	V _{GS} = 10V, I _D = 5A	-	0.76	1.1	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2	3	4	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	2	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V	-	1450	-	pF
C _{OSS}	Output Capacitance	V _{DS} = 25V	-	150	-	
C _{RSS}	Reverse Transfer Capacitance	f = 1MHz	-	12	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time ^{*3}	V _{DD} = 350V	-	15	-	ns
t _r	Turn-on Rise Time ^{*3}	V _{GS} = 10V	-	25	-	
t _{d(OFF)}	Turn-Off Delay Time ^{*3}	I _D = 10A	-	51	-	
t _f	Turn-Off Fall Time ^{*3}	R _G = 9.1Ω	-	31	-	
Q _G	Total Gate-Charge	V _{DD} = 560V	-	43	-	nC
Q _{GS}	Gate to Source Charge	V _{GS} = 10V	-	6.6	-	
Q _{GD}	Gate to Drain (Miller) Charge	I _D = 10A	-	21	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage ^{*1}	I _{SD} = 10A, V _{GS} = 0V	-	0.86	1.5	V
t _{rr}	Reverse Recovery Time	I _{SD} = 10A, V _{GS} = 0V	-	550	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt = 100A/μs	-	5.6	-	μC

Notes:

1. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
2. The E_{AS} data shows Max. rating. The test condition is V_{DD} = 100V, V_{GS} = 15V, L = 50mH
3. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

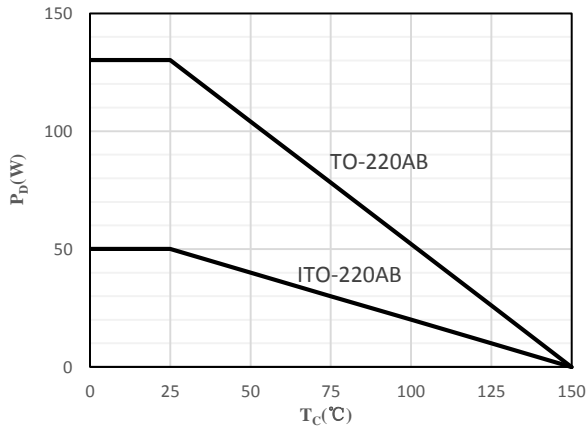


Fig 1 Power Dissipation

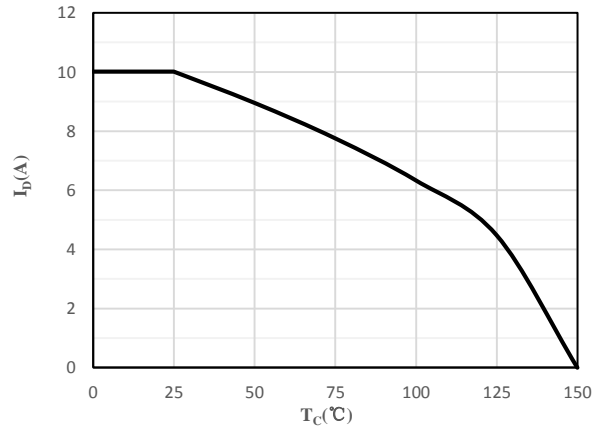


Fig 2 Drain Current

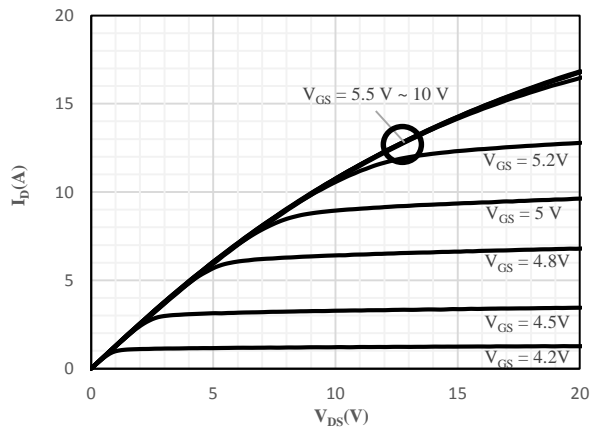


Fig 3 Typical Output Characteristics

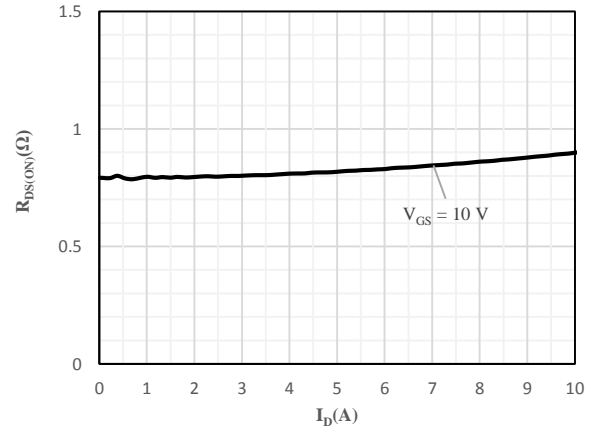


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

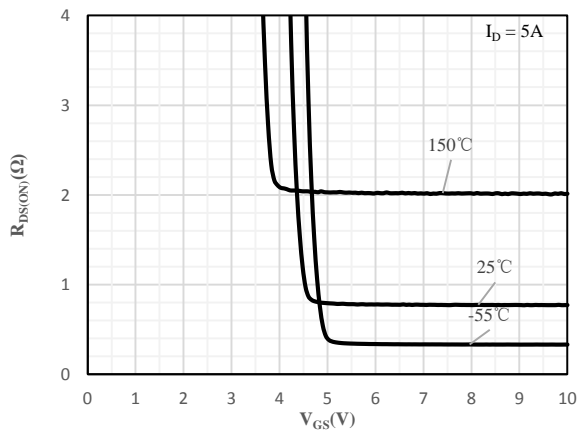


Fig 5 On-Resistance vs. Gate-Source Voltage

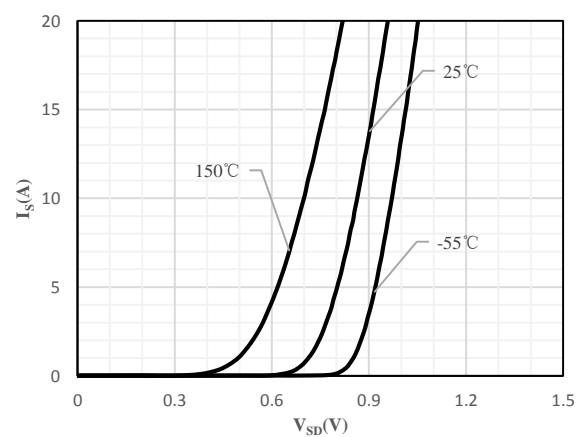


Fig 6 Body-Diode Characteristics

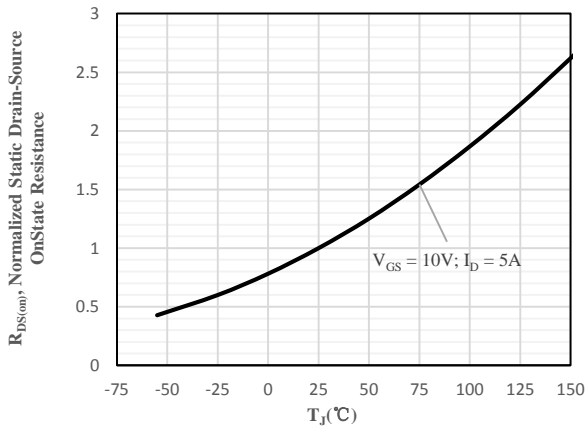


Fig 7 Normalized On-Resistance vs. Junction Temperature

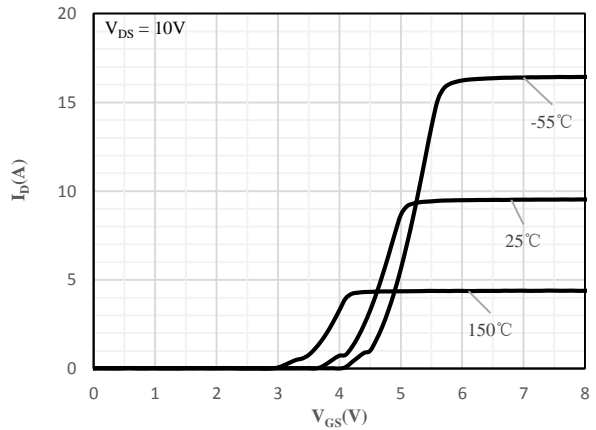


Fig 8 Transfer Characteristics

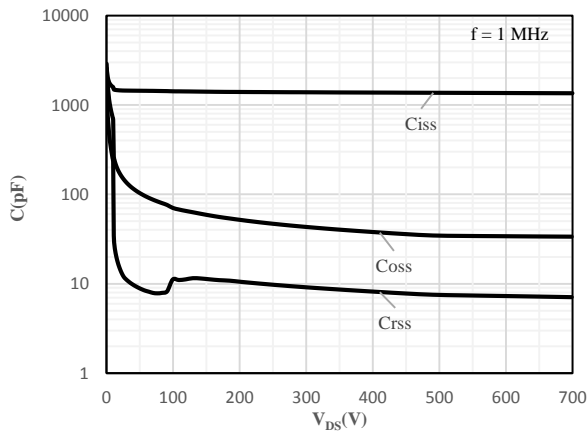


Fig 9 Capacitance Characteristics

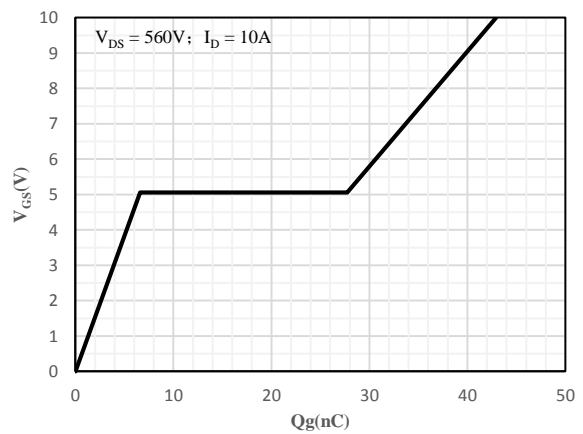


Fig 10 Gate-Charge Characteristics

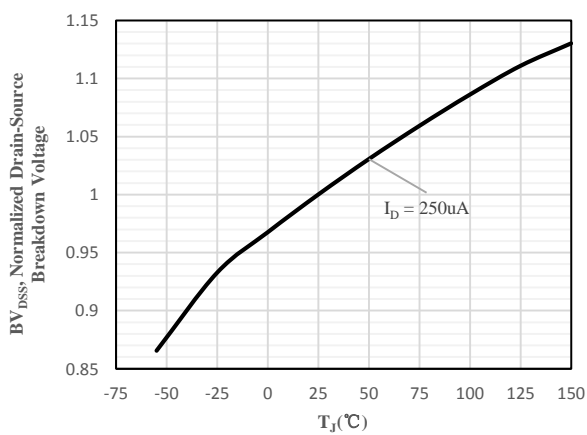


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

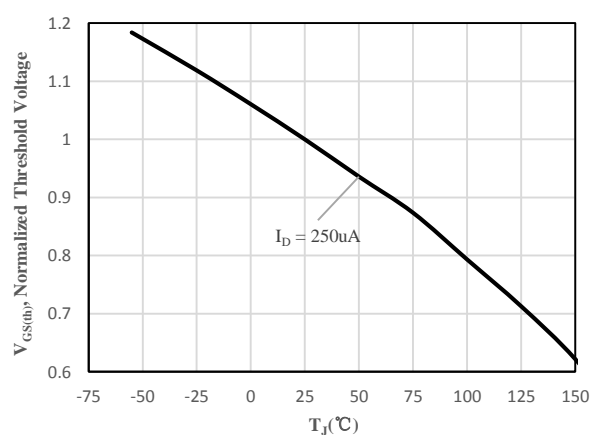


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

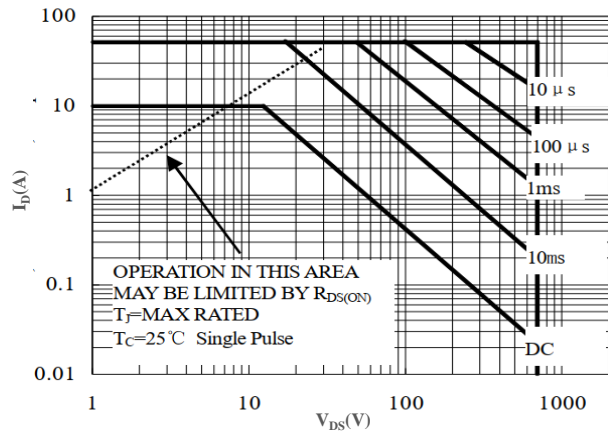


Fig 13 Safe Operation Area (TO-220AB)

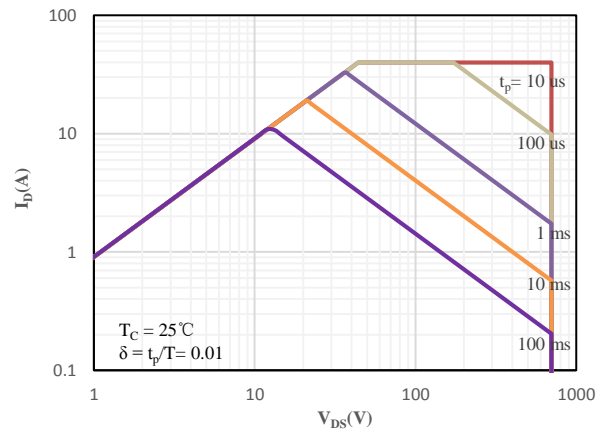


Fig 14 Safe Operation Area (ITO-220AB)

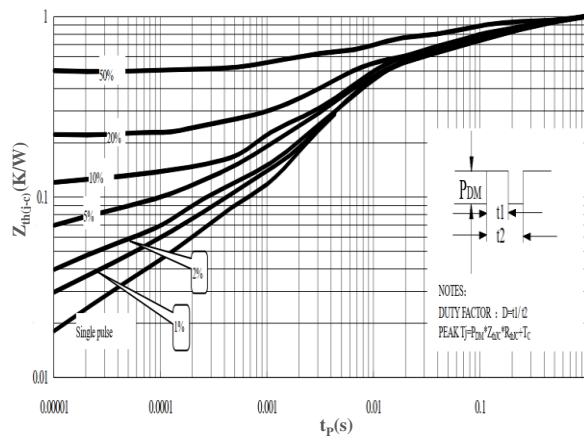


Fig 15 Maximum transient thermal impedance
(TO-220AB)

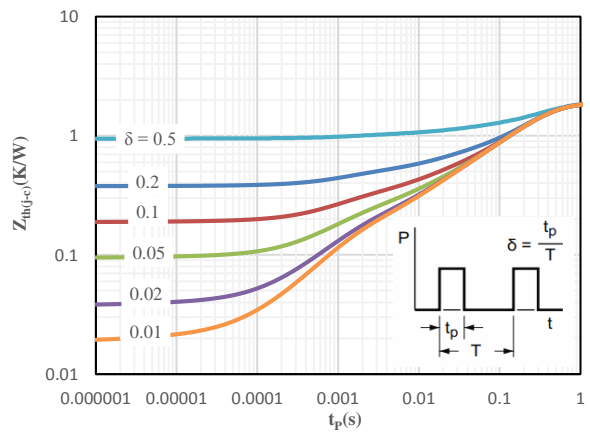


Fig 16 Maximum transient thermal impedance
(ITO-220AB)

Package Outline Dimensions (Unit: mm)

		TO-220AB		
Dimension		Min.	Max.	
A		9.80	10.30	
B		8.70	9.10	
C		4.37	4.77	
D		1.07	1.47	
E		2.64	2.84	
F		13.14	13.74	
G		2.44	2.64	
H		28.03	28.83	
I		3.50	4.00	
J		0.28	0.48	
K		1.22	1.32	
L		0.71	0.91	
M		2.40	2.60	
N		3.76	3.96	

		ITO-220AB		
Dimension		Min.	Max.	
A		9.90	10.30	
B		14.80	15.20	
C		4.30	4.70	
D		2.50	2.90	
E		2.80	3.30	
F		13.00	13.60	
G		3.10	3.30	
H		28.00	28.60	
I		7.90	8.90	
J		0.40	0.60	
L		0.70	0.90	
M		1.30	1.50	
N		2.60	2.80	
O		2.60	3.10	
P		2.45	2.65	
K/R		1.10	1.30	

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